

## Day 1 - Tuesday 9th November 2021

08:00 Registration and welcome refreshments.

08:50 Housekeeping by Michael Lebby and David Cheskis

### PICs Today ▯ Datacom, Sensing & LiDAR

09:00 **PICs for LIDAR**  
*ommatidia lidar, EPIC, Ibeo Automotive Systems GmbH, Freedom Photonics, and Rockley Photonics*

**PANEL SESSION**

09:30 **Sensors and Systems for Next Generation 3D Imaging & LiDAR Applications**  
*Presented by Wade Appelman - ON Semiconductor*

**PANEL SESSION**

09:45 **Silicon Photonics, beyond the tipping point!**  
*Presented by Eric Mounier - Yole Développement*

**PANEL SESSION**

10:00 **Presentation Title to be Confirmed**

**PANEL SESSION**

10:15 **Novel electro-optical substrate enabling cost effective PIC assembly solutions for sensor and communication applications**  
*Presented by Felix Betschon - Vario-optics*

**PANEL SESSION**

10:30 **PICs for data-center interconnects**  
*Presented by Benjamin Wohlfeil - ADVA Optical Networking*

**PANEL SESSION**

10:45 **Integrated 4D Machine Vision**  
*Presented by Mehdi Asghari - SiLC*

11:00 Morning Break - Sponsored by Hewlett Packard Enterprise

**PANEL SESSION**

11:30 **Hybrid Photonic Integration for Sensing and Communications**  
*Presented by Martin Schell - Fraunhofer HHI*

**PANEL SESSION**

11:45 **Automotive, LiDAR & MedTech – Providing access & experiences gained**  
*Presented by Ignazio Piacentini - ficonTEC*

**PANEL SESSION**

12:00 **From Prototypes to Production: Compact packaging of miniaturized light sources**  
*Presented by Ruth Houbertz - Multiphoton Optics*

**PANEL SESSION**

12:15 **Silicon Photonics for automotive LIDAR applications**  
*Presented by Robert Blum - Intel*

**PANEL SESSION**

12:30 **An overview of a variety of cutting edge PICs for sensing applications**  
*Presented by Paul Leisher - Freedom Photonics*

12:45 Lunch Break - Sponsored by Hewlett Packard Enterprise

**PANEL SESSION**

14:00 **Plasmonics in CMOS foundries: a new toolkit for PICs**  
*Presented by Nikos Pleros - Aristotle University of Thessaloniki*

**PANEL SESSION**

14:15 **Presentation Title to be Confirmed - Synopsys**  
*Presented by Twan Korthorst - Synopsys*

### PIC Manufacturing ▯ TAP, Co-Packaging & Fab

**PANEL SESSION**

14:30 **Si-Based Photonic platform at CEA – Leti**  
*Presented by Sergio Nicoletti - CEA-Leti*

**PANEL SESSION**

**14:45** SiN goes thick enabling PIC applications  
*Presented by Michael Geiselmann - LIGENTEC*

**PANEL SESSION**

**15:00** Silicon nitride based TriPleX™ modules with hybrid PIC integration  
*Presented by Arne Leinse - LioniX International*

**PANEL SESSION**

**15:15** CORNERSTONE – The scalable rapid prototyping platform  
*Presented by Graham Reed - Cornerstone, University of Southampton*

**PANEL SESSION**

**15:30** Scaling up photonic integration: validating designs, chips and assemblies  
*Presented by Iñigo Artundo - VLC Photonics*

**PANEL SESSION**

**15:45** Spectral characterization: challenges, solutions and the future of PIC optical testing  
*Presented by François Couny - EXFO*

**PANEL SESSION**

**16:00** Presentation Title to be Confirmed

**16:15** Does volume drive photonics integration?  
*Bill Ring, EFFECT Photonics, Yole Développement, AEPONYX inc, Luxtera, and Intel*

**17:05** Networking Drinks Reception

## Day 2 - Wednesday 10th November 2021

08:00 Registration and welcome refreshments.

08:50 Housekeeping by Michael Lebby and David Cheskis

### PIC Technology ▯ Solutions, Analysis & Research

#### PANEL SESSION

09:00 **Cost-effective high-power laser-on-silicon technology for LiDAR applications**  
*Presented by Dongjae Shin - Samsung*

#### PANEL SESSION

09:15 **Photonics Then & Now; Why Now But Not Then?**  
*Presented by David Banas - Luminous Computing*

#### PANEL SESSION

09:30 **Additive microfabrication for optical packaging**  
*Presented by Jochen Zimmer - Nanoscribe*

#### PANEL SESSION

09:45 **Innovations in fiber to chip connectivity**  
*Presented by Scott Bickham - Corning Optical Communications*

#### PANEL SESSION

10:00 **Design, modeling and simulation for the imperfections of real life**  
*Presented by James Pond - Lumerical*

10:15 Morning Break - Sponsored by Hewlett Packard Enterprise

#### PANEL SESSION

10:45 **Coherent vs. Direct-Detection: Market Forces Shaping PIC Technology Beyond 400 G**  
*Presented by Vipul Bhatt - II-VI*

#### PANEL SESSION

11:00 **Coping with the diversity of technologies and applications in CAD environments**  
*Presented by André Richter - VPIphotonics*

#### PANEL SESSION

11:15 **OptiSPICE Plugin: A SPICE Native Optical Model Library for Opto-Electronic Design Automation**  
*Presented by Cem Bonfil - Optiwave*

### PICs Vision ▯ Evolution and Revolution

#### PANEL SESSION

11:30 **AIM's role in developing next-gen PICs and TAP manufacturing expertise**  
*Presented by Frank Tolic - AIM Photonics*

#### PANEL SESSION

11:45 **Presentation Title to be Confirmed**

#### PANEL SESSION

12:00 **InP PICs and their future network & market applications**  
*Presented by Mehrdad Ziari - Infinera*

#### PANEL SESSION

12:15 **Elenion Technologies - Presentation Title TBC**  
*Presented by Michael Hochberg - Elenion Technologies*

12:30 Lunch Break - Sponsored by Hewlett Packard Enterprise

#### PANEL SESSION

13:45 **Presentation Title to be Confirmed**

#### PANEL SESSION

14:00 **Integrated photonics for neuromorphic computing**  
*Presented by Bert Offrein - IBM*

#### PANEL SESSION

14:15 **Optical transceiver manufacturing in the electronics ecosystem – lessons learned and the road ahead**  
*Presented by Ted Schmidt - Juniper Networks*

#### PANEL SESSION

14:30 **Increasing power efficiency with Electro-optic (EO) Polymers**  
*Presented by Michael Lebby - Lightwave Logic Inc*

**PANEL SESSION**

15:00 **Invest in your design flow**  
*Presented by Martin Fiers - Lucedo Photonics*

**PANEL SESSION**

15:15 **Presentation Title to be Confirmed - Smart Photonics**  
*Presented by Luc Augustin - Smart Photonics*

**PANEL SESSION**

15:30 **Future and economics of PICs and PLCs in PON systems for data centre and mobile backhaul applications**  
*Presented by Henk Bultuis - Broadex Technologies*

**PANEL SESSION**

15:45 **Assessing the long-term growth and market potential for PICs in datacom, transport and networks**  
*Presented by Eric Higham - Strategy Analytics*

16:00 **Closing Remarks**

